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(12) **United States Design Patent** (10) **Patent No.:** **US D568,841 S**
Fischer et al. (45) **Date of Patent:** **** May 13, 2008**

(54) **ENCLOSURE FOR ELECTRONIC COMPONENTS**
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(**) Term: **14 Years**

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(51) **LOC (8) Cl.** **13-03**
(52) **U.S. Cl.** **D13/184**
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D14/353, 356, 357, 368, 433, 434, 435, 240,
D14/137, 142, 358, 241, 242, 243, 256, 140.1,
D14/238; 455/73, 90.3, 151.1, 347, 554.1;
379/413.04, 428.01, 447; 220/4.01; 174/16.3;
361/704, 274.3, 271, 697, 702, 709-711,
361/719, 720, 514

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for an enclosure for electronic components, as shown and described.

DESCRIPTION

FIG. 1 is an elevated perspective view of an enclosure for electronic components incorporating a design according to the invention.

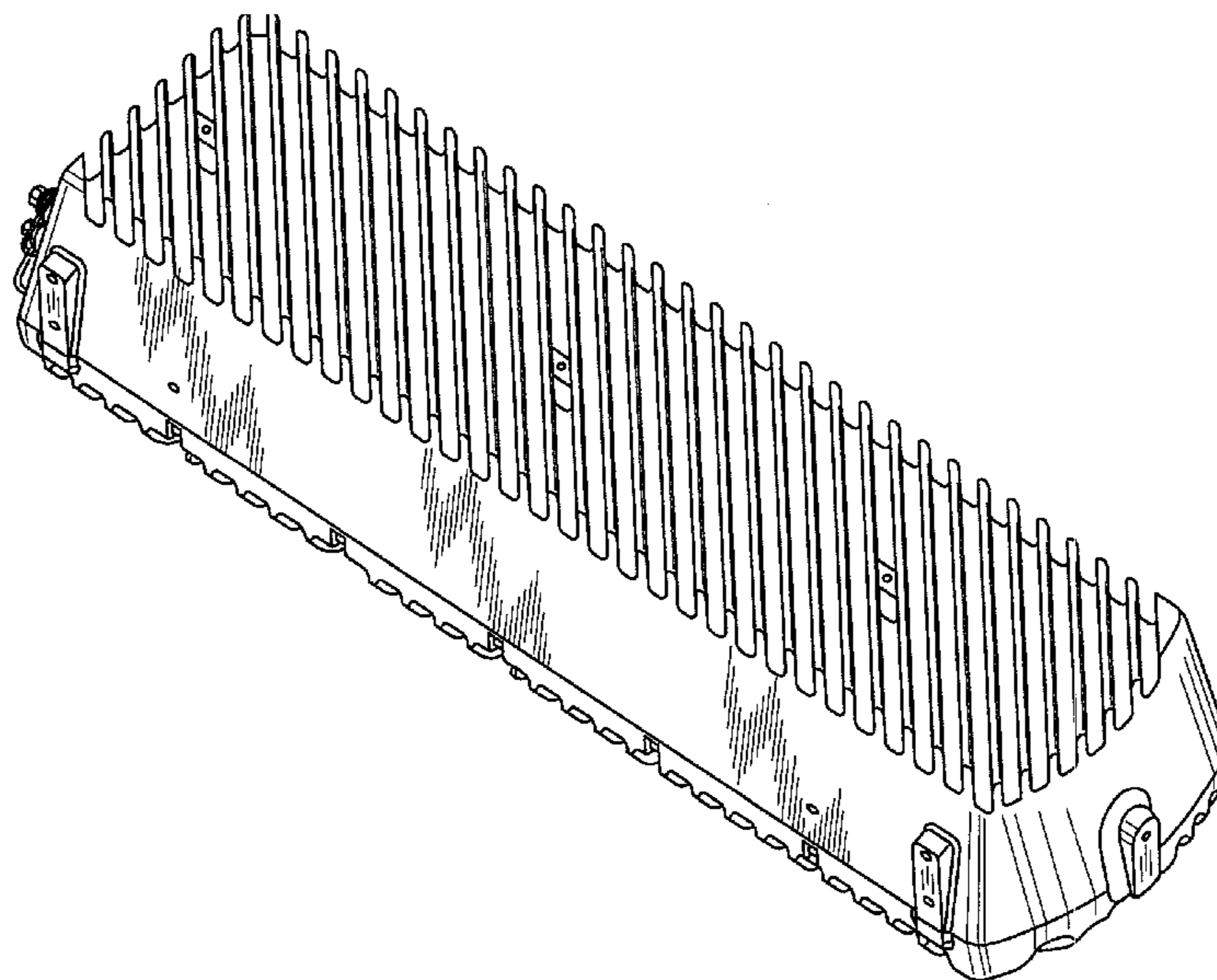
FIG. 2 is a left side view of the enclosure of FIG. 1.

FIG. 3 is a right side view of the enclosure of FIG. 1.

FIG. 4 is an end view of the enclosure of FIG. 1; and,

FIG. 5 is a bottom view of the enclosure of FIG. 1.

1 Claim, 5 Drawing Sheets



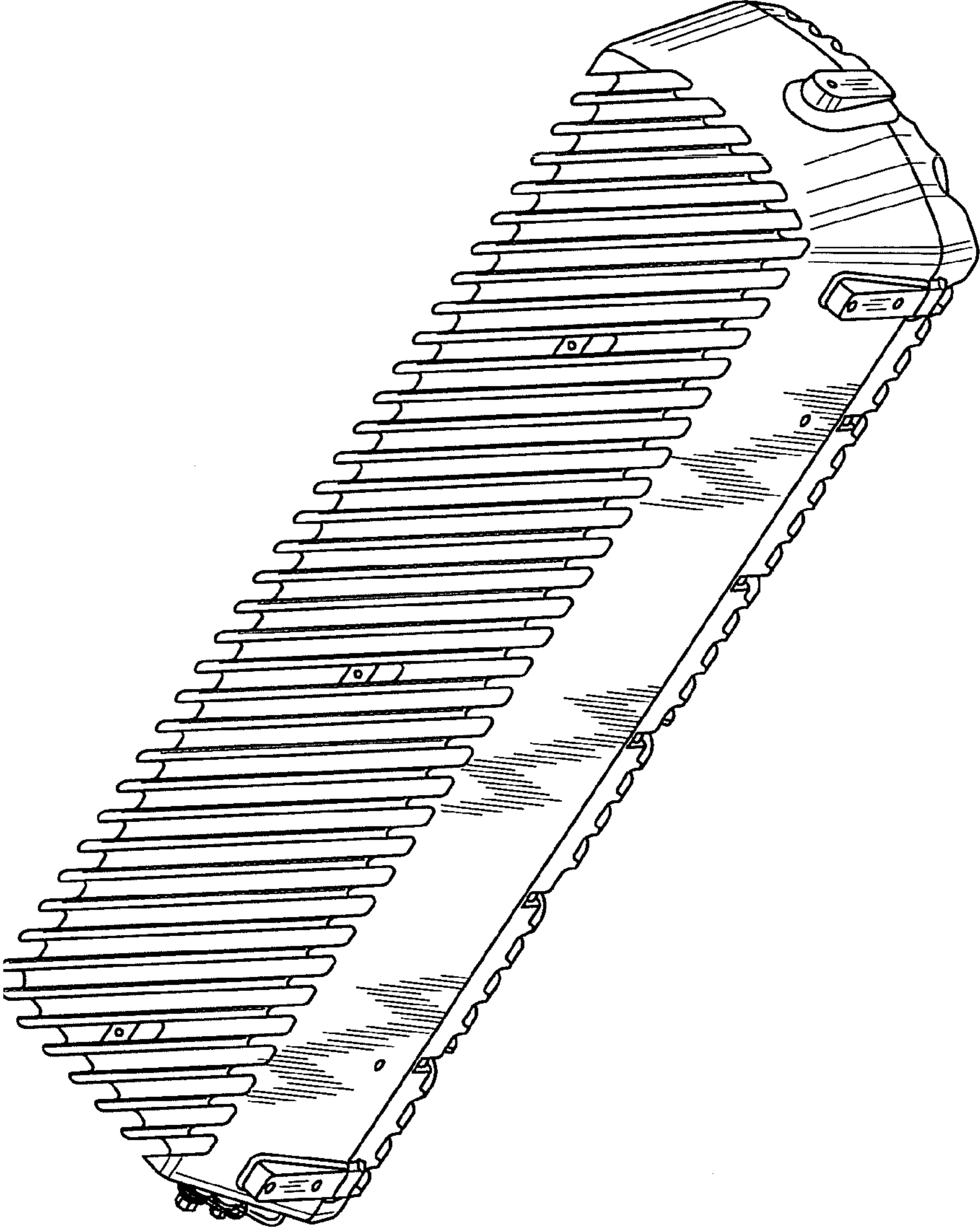


Fig. 1

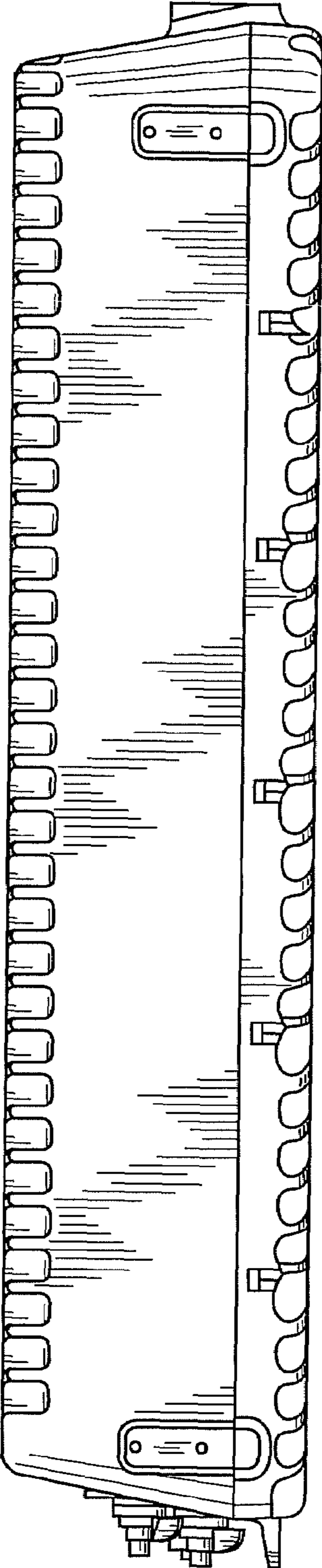


Fig. 2

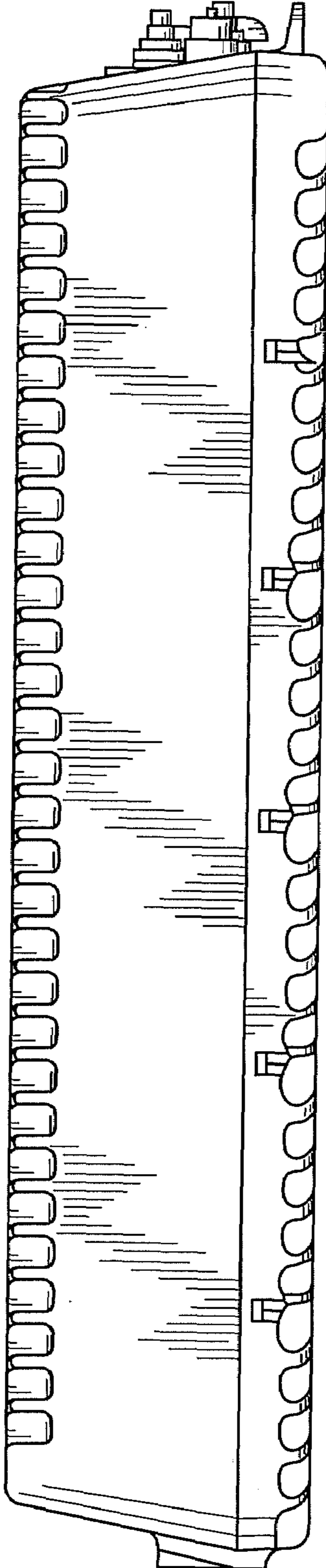


Fig. 3

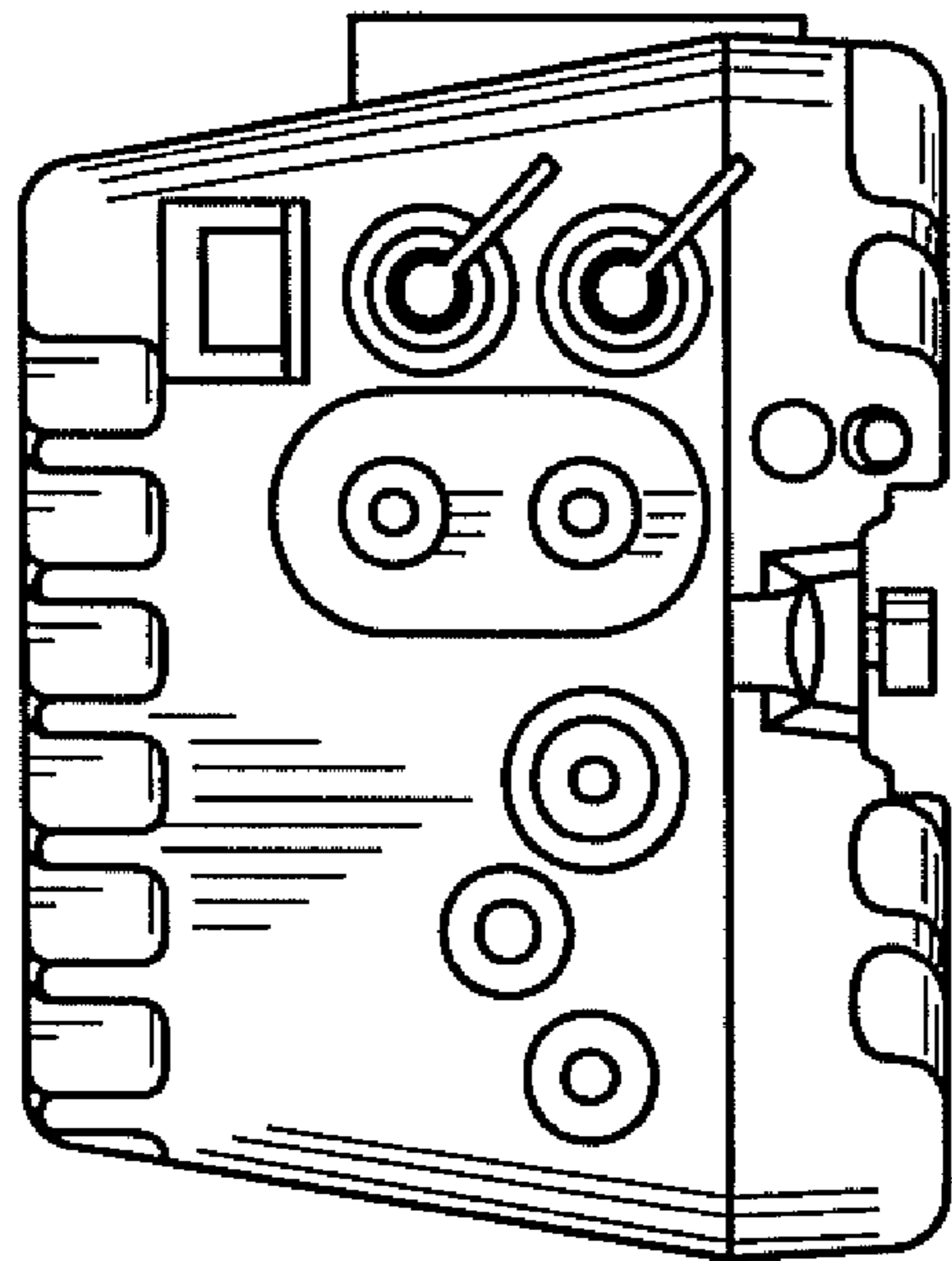


Fig. 4

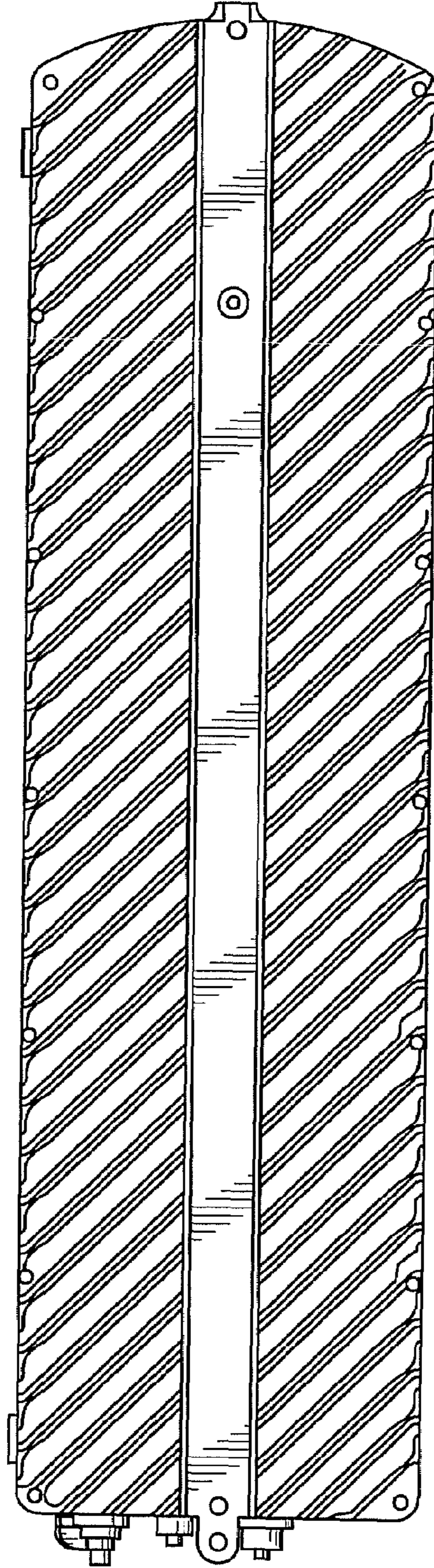


Fig. 5